

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	1085	(lead near2 frame) with (seal\$4 or clos\$4 or encapsulat\$4 or fasten\$4) with (resin or epoxy) with (cavit\$3 or via\$3 or hole\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/19 13:50
2	BRS	L2	54192	"lead frame"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/19 13:51
3	BRS	L3	618	(seal\$4 near2 resin) near8 (cavit\$4) near8 mold\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/19 13:51
4	BRS	L4	157	3 same 2	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/19 13:52
5	IS&R	L6	983	(438/123).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/19 14:23

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	IS&R	L7	3466	(257/666) .CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/19 14:24
7	BRS	L8	4458	5 or 6 or 7	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/19 14:24
8	BRS	L9	43	3 and 8	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/19 14:24
9	IS&R	L10	335	(438/111) .CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/19 14:40

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L2	1023	(lead near2 frame) with (seal\$4 or clos\$4 or encapsulat\$4 or fasten\$4) with (resin or epoxy) with (cavit\$3 or via\$3 or hole\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 01:22
2	IS&R	L3	310	(438/111).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 01:22
3	BRS	L7	37	((lead near2 frame) near8 (seal\$4 or clos\$4 or encapsulat\$4 or fasten\$4) near8 (resin or epoxy) near8 (cavit\$3 or via\$3 or hole\$3)) and ((257/666).CCLS.)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 01:22
4	BRS	L1	484	(lead near2 frame) near8 (seal\$4 or clos\$4 or encapsulat\$4 or fasten\$4) near8 (resin or epoxy) near8 (cavit\$3 or via\$3 or hole\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 01:22
5	BRS	L6	5	((lead near2 frame) near8 (seal\$4 or clos\$4 or encapsulat\$4 or fasten\$4) near8 (resin or epoxy) near8 (cavit\$3 or via\$3 or hole\$3)) and ((438/111).CCLS.)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 01:22

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L8	16	((lead near2 frame) near8 (seal\$4 or clos\$4 or encapsulat\$4 or fasten\$4) near8 (resin or epoxy) near8 (cavit\$3 or via\$3 or hole\$3)) and ((438/123).CCLS.)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 01:22
7	IS&R	L4	906	(438/123).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 01:44
8	IS&R	L9	3340	(257/666).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 02:23

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L63	37	((lead near2 frame) near8 (seal\$4 or clos\$4 or encapsulat\$4 or fasten\$4) near8 (resin or epoxy) near8 (cavit\$3 or via\$3 or hole\$3)) and ((257/666).CCLS.)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 06:51
2	BRS	L106	2	(lead adj frame) same (seal\$4 near2 resin) same (outer adj lead) same (inner adj lead) same (hard\$8 near4 resin)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 07:13
3	BRS	L107	572	(seal\$4 near2 resin) near8 (cavit\$4) near8 mold\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 07:14
4	BRS	L108	51642	"lead frame"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 07:14
5	BRS	L109	146	107 same 108	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 07:32

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L110	0	107 with (spacer\$3) with (groov\$4 or gap\$4 or via or vias or hole or holes or channel\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 07:33
7	BRS	L111	1	107 same (spacer\$3) same (groov\$4 or gap\$4 or via or vias or hole or holes or channel\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 07:34
8	BRS	L112	136	107 same (groov\$4 or gap\$4 or via or vias or hole or holes or channel\$3)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 07:34
9	BRS	L113	98	112 not 109	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/09/22 07:35